F3MM

特点（characteristic）：

* ˆ L/W/H˜ :10.0*9.0*4.5mm

Appearance dimension (L / w / h):10.0*9.0*4.5mm

* ὖ ὼ ἵ r : / r

Luminous color and colloid: Red Green Light /Red Green colloid

* Ḡ° ჯ˘ ROHS

Environmental protection products meet ROHS requirements

* ˆ MSL˜ :2

Moisture sensitivity levelʃ MSL˜ : 2 levels

* EIA ‰´

EIA standard packaging

* ą ث

Long operating life

* ɣ

Reduced maintenance costs

* à Ƣ˗

High energy efficiency, fast startup

应用领域（product application）

*

Internet of Things

* ɣ

medical treatment

* ლ

converter

* Ũ Ⱶ ლ ɇ Ḥ

Storage servers and communication

* ლ

Status indicator

* ת ლ

Electronic testing instruments

目录

Catalogue

电性参数

Electrical Characteristics

ώ ǎ Initial Electrical Optical Characteristics ˆ Ta=25 ˜

ǎ Parameter	´ Symbol	Color.	ỵ Min.	w̄ ỵ Typ.	ỵ Max.	ł β Unit.	Đ Test Conditions
ŭ ώ ˆ Luminous Intensity˜	Iv	R	/	500	/	mcd	IF=20mA
		YG	/	100	/		
h ˆ Dominant Wave Length˜	êd	R	620	/	625	nm	IF=20mA
		YG	565	/	575		
ỵ ˆ Peak Wave Length˜	êp	R	/	625	/	nm	IF=20mA
		YG	/	570	/		
h ł ˆ Forward Voltage˜	VF	R	1.8	/	2.4	V	IF=20mA
		YG	1.8	/	2.6		
ł ˆ Half wave width˜							

Brightness grading:

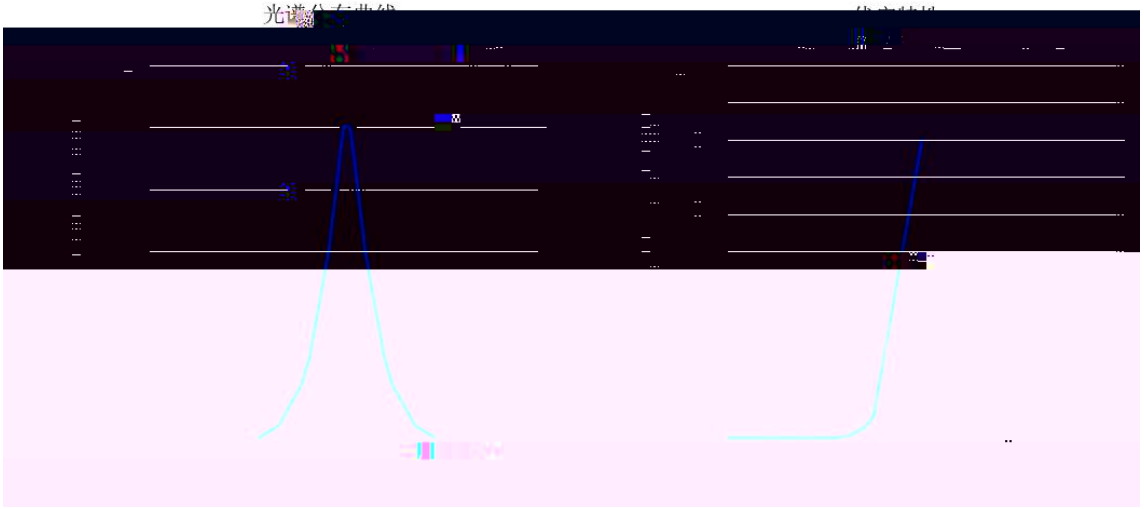
Code	Min

电压分档:
Voltage grading:

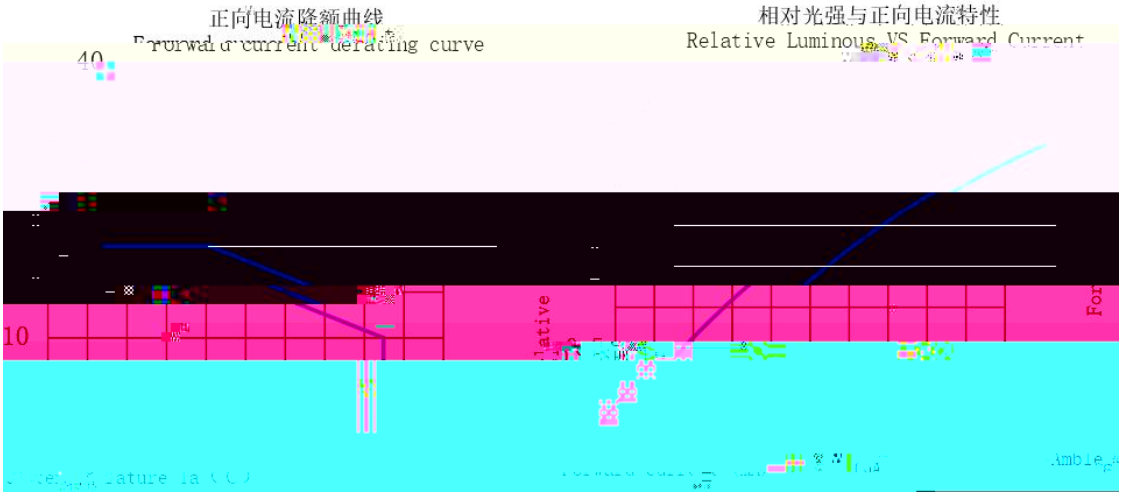
波长分档:
Wavelength grading:

典型特性曲线

Typical Characteristics Curves



正向电流降额曲线



相对光强与正向电流特性

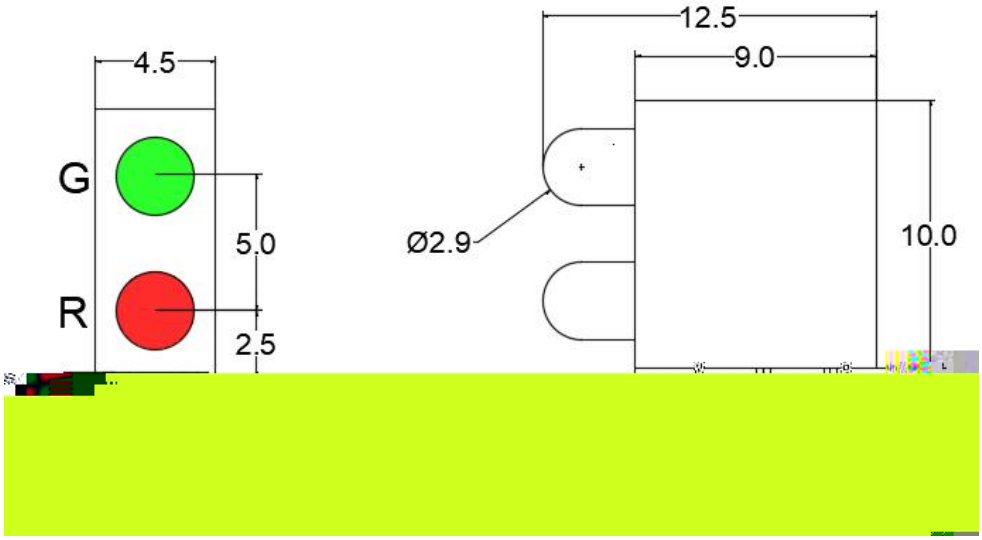
ч 25 + 5 C./Note: If not otherwise indicated, the test environment temperature is 25 + 5 C.

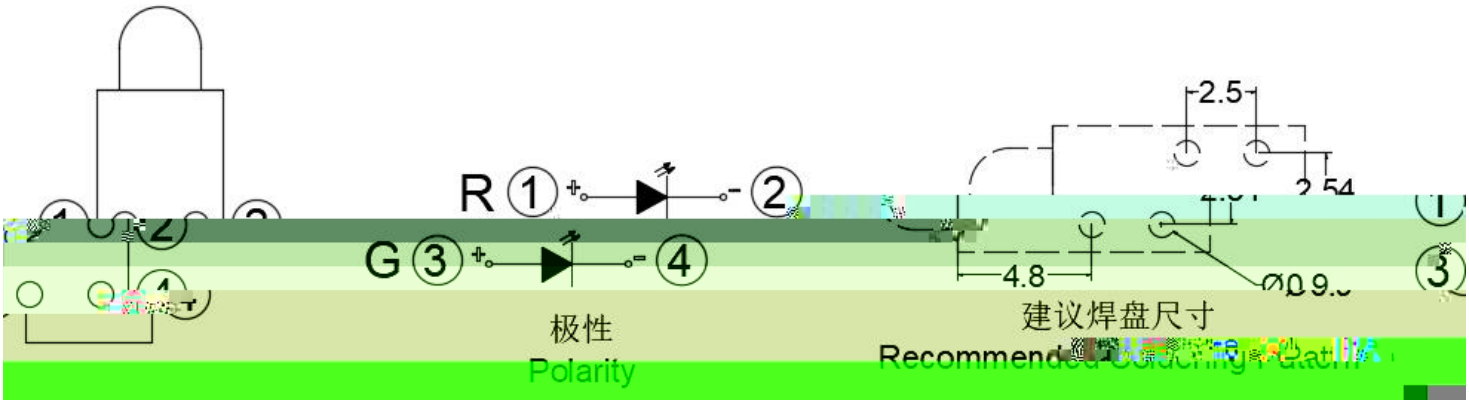
XL-DZ304SYGSURD/G

3 ˇ 4 25 + 5 C./Note: If not otherwise indicated, the test jndir

外形尺寸

Outline Dimension





(Note)'

1. ¥ β ч

Dimensions are in millimeters.

2. ≠ ˘ "Ḥ È Ñ 0.25mm .

Tolerances unless mentioned are Ñ 0.25mm.

包装

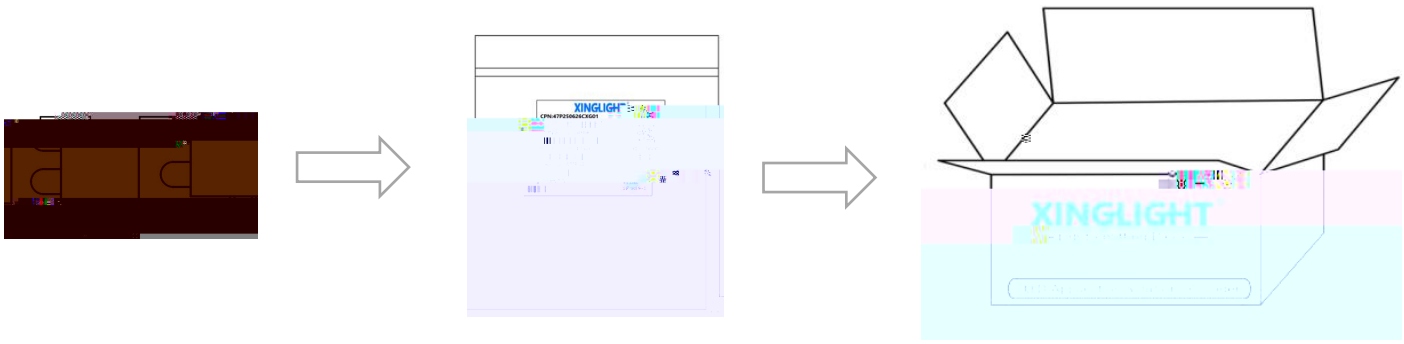
Packaging

*

In Bags

*

Moisture Proof and Anti-Electrostatic Foil Bag



使用注意事项：

使用注意事项（2）

Precautions (2)

Design Consideration

*

使用注意事项（3）

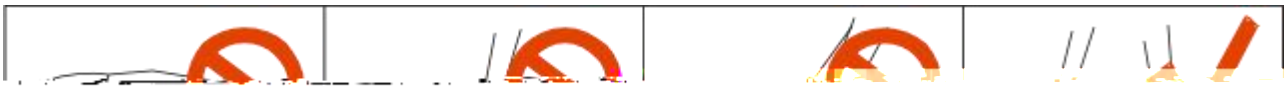
Precautions (3)

4、其他事项：

Others:

* Ü ç b p ψ ˇ Ä G ج ç Í Â ı z Ä ڑ ṗ
é ˇ ج ~ ç ∀ ı z ˇ ≠ ç G Ÿ p ضج Ţ Â

*When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



*LED № ˇ ~ à r ⌂ à № Â ض ŭ Ŗ Ä
Â

*The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.